

Sputter Parameters

<u>Target</u>	<u>Deposition Rate (nm/min)</u>	<u>Power (W)</u>	<u>Ramp Rate (W/s)</u>	<u>Temperature (°C)</u>	<u>Pressure (mT)</u>	<u>Gas Flow (sccm)</u>
Ag	3.33	25	0.5	200	6	30 Ar
Al		375	1.5	0	3	30 Ar
Cr		155-290	1.0	0	3-10	30 Ar
Cu		200-420	1.5	0	3	30 Ar
SiO ₂		188	1.0	0	3	30 Ar
ZnO		180	0.6	150	2	13.5 Ar 1.5 O ₂
Al		100	2.0	0	3	30 Ar
ITO	2.00	45	0.15	150-200	5	28 Ar 2 O ₂
LiNbO ₃		60	0.35	450	3-30	30 Ar
AlSi		375	1.5	0	3	30 Ar
Mo		200	1.0	200	10	30 Ar
MoSi ₂		130	0.55	0	3	30 Ar
Nb		75-220	0.75	0	3	30 Ar
NbN		100		0	3	30 Ar
Ni		300	1.25	0	6	30 Ar
Si		190	0.5	0	10	30 Ar
SiO ₂	1.66	188	0.39	0	2	30 Ar
Ti		150-200	0.5	0	3	30 Ar
TiO ₂		60-150	0.5	0	3	30 Ar
W		290	1.6	0	3	30 Ar
ZnO		20-100	0.40	0	3	30 Ar

Please add/modify/clarify parameters that work well for your process and this tool! – NanoFab Staff